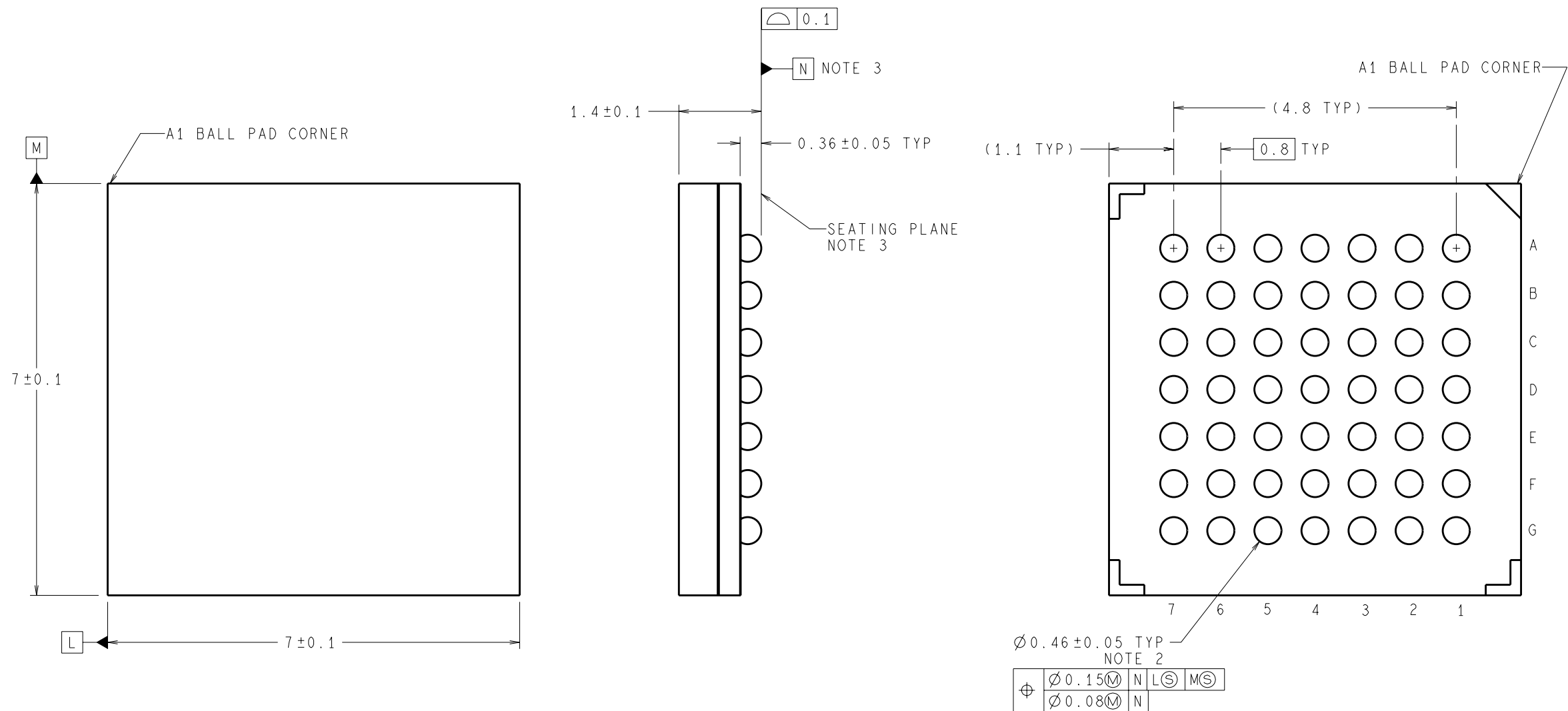


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12253	08/14/2000	TL/GN



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
2. DIMENSION MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
3. PRIMARY DATUM N AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. NO JEDEC REGISTRATION AS OF JULY 2000.

APPROVALS		DATE	National Semiconductor		
DRAWN	T. LEQUANG	08/14/2000	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DFTG. CHK.	MARTA SUCHY	08/14/2000	FBGA, PLASTIC, LAMINATED, 7 X 7 X 1.4 mm BODY, 49 BALL, 0.8 mm PITCH		
ENGR. CHK.	GLENN NARVAEZ	08/14/2000			
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-SLC49A	A
DO NOT SCALE DRAWING			SHEET 1 of 1		